

Bill of Materials

TI DESIGNS

TIPD185: AC Coupled Single-Supply Amplifier Reference Design

Line	Quantity	Designator	Description	Manufacture	Part Number	Supplier Part Number
1	3	C1, C3, C6	CAP, CERM, 10 μ F, 25 V, +/- 10%, X7R, 1210	AVX Corporation	12103C106KAT2A	478-5728-1-ND
2	3	C2, C5, C7	CAP, CERM, 0.1 μ F, 25 V, +/- 10%, X5R, 0603	AVX Corporation	06033D104KAT2A	478-1244-1-ND
3	1	C4	CAP, TA, 10 μ F, 50 V, +/- 10%, 0.8 ohm, SMD	Vishay Sprague	293D106X9050E2TE3	718-1022-1-ND
4	1	J1, J2	CONN BNC JACK R/A 50 OHM PCB	TE Connectivity	1-1634612-0	A97555-ND
5	1	J3, J4	JACK NON-INSULATED .218", Banana Jack	Keystone Electronics	575-4	575-4K-ND
6	2	JMP1, JMP2	SHUNT LP W/HANDLE 2 POS 30AU	TE Connectivity	JUMP3	A26242-ND
7	2	JMP1, JMP2	CONN HEADER 50POS .100" SGL GOLD	Samtec Inc	JUMP3	SAM1029-50-ND
8	1	R1	RES SMD 1.13K OHM 1% 1/8W 0805	Vishay Dale	CRCW08051K13FKEA	541-1.13KCCT-ND
9	1	R2	RES SMD 10.2K OHM 1% 1/8W 0805	Vishay Dale	CRCW080510K2FKEA	541-10.2KCCT-ND
10	5	R3, R4, R6, R7, R8	RES, 10.0 k, 1%, 0.125 W, 0805	Vishay Dale	CRCW080510K0FKEA	541-10.0KCCT-ND
11	1	R5	RES, 1.00 k, 1%, 0.125 W, 0805	Vishay Dale	CRCW08051K00FKEA	541-1.00KCCT-ND
12	2	R9, R10	RES, 49.9, 1%, 0.125 W, 0805	Vishay Dale	CRCW080549R9FKEA	541-49.9CCT-ND
13	3	TP1, TP2, TP3	Test Point, TH, Compact, Red	Keystone Electronics	5005	5005K-ND
14	3	TP4, TP5, TP6	Test Point, TH, Compact, Black	Keystone Electronics	5006	5006K-ND
15	2	U1, U2	IC OPAMP GP 5.5MHZ RRO 8SOIC	Texas Instruments	OPA376AID	296-22190-5-ND
16	4		STANDOFF HEX 4-40THR ALUM 1L"	Keystone Electronics	2205	2205K-ND
17	4		MACHINE SCREW PAN PHILLIPS 4-40	B&F Fastener Supply	PMSSS 440 0025 PH	H703-ND

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